

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)
2. (Previously Presented) An optical module comprising:
  - an interconnect board which includes a base board and an interconnecting pattern formed on the base board;
  - an optical chip which includes an optical section and an electrode which electrically connects the optical section and the interconnecting pattern; and
  - a body material which holds a lens which concentrates light on the optical section,
    - wherein the body material is directly attached to the optical chip,
    - wherein an opening is formed in the base board,
    - wherein the optical chip is bonded face down to the interconnect board so that the optical section faces the opening, and
    - wherein the body material is attached to the optical chip through the opening.
3. (Canceled)
4. (Previously Presented) An optical module comprising:
  - an interconnect board which includes a base board and an interconnecting pattern formed on the base board;
  - an optical chip which includes an optical section and an electrode which electrically connects the optical section and the interconnecting pattern;
  - a body material which holds a lens which concentrates light on the optical section; and

- a resin section which is provided between the body material and the interconnect board to bond the body material to the interconnect board,  
wherein the body material is directly attached to the optical chip.
5. (Original) The optical module as defined in claim 4,  
wherein the optical chip is bonded face up to the interconnect board,  
wherein the electrode and the interconnecting pattern are electrically connected through a wire, and  
wherein the resin section seals at least the wire.
6. (Original) The optical module as defined in claim 5,  
wherein a space having a shape which surrounds the wire, and a hole which has a width smaller than a width of the space and opens to an outside from the space are formed in the body material, and  
wherein the space is filled with the resin section.
- 7-9. (Canceled)
10. (Previously Presented) An optical module comprising:  
an interconnect board which includes a base board and an interconnecting pattern formed on the base board;  
an optical chip which includes an optical section and an electrode which electrically connects the optical section and the interconnecting pattern; and  
a body material which holds a lens which concentrates light on the optical section,  
wherein the body material is directly attached to the optical chip,  
wherein the body material is bonded to the optical chip through an adhesive sheet material.

11. (Previously Presented) An optical module comprising:

an interconnect board which includes a base board and an interconnecting pattern formed on the base board;

an optical chip which includes an optical section and an electrode which electrically connects the optical section and the interconnecting pattern; and

a body material which holds a lens which concentrates light on the optical section,

wherein the body material is directly attached to the optical chip,

wherein the body material is bonded to the optical chip through an adhesive.

12. (Previously Presented) An electronic instrument comprising the optical module as defined in claim 2.

13. (Canceled)